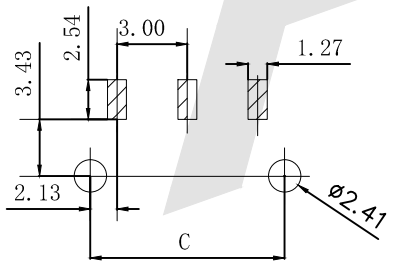
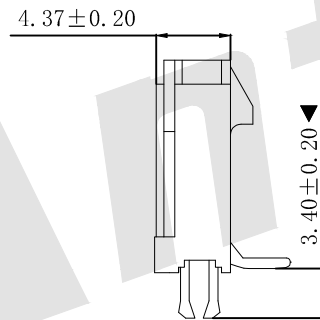
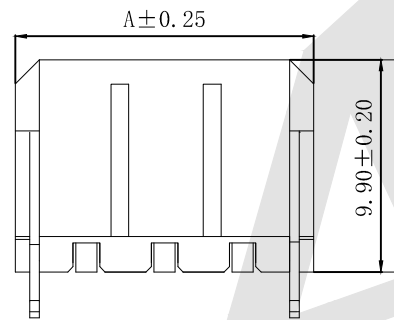
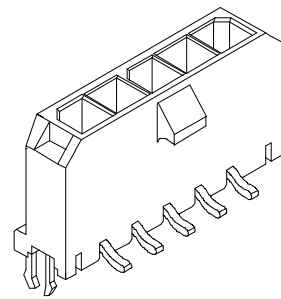
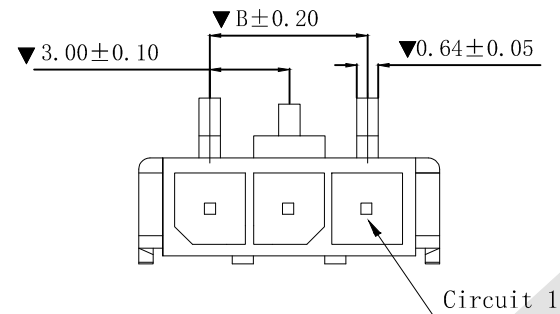
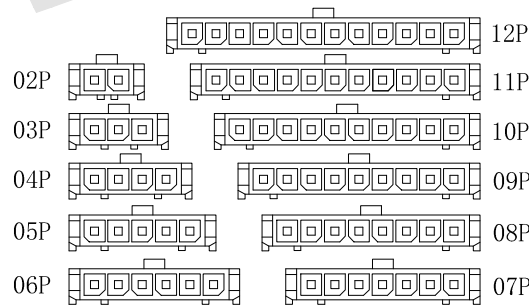


HSF



P. C. B. LAYOUT



CIRCUIT SIZE LAYOUT

SPECIFICATIONS

- Voltage rating: 250V AC/DC
 - Current rating: 5A, AC, DC
 - Withstanding Voltage: 1500V AC/minute
 - Insulation resistance: 1000MΩ min
 - Temperature range: -25°C~+85°C
 - Contact resistance: 20mΩ max
- WAFER
- Part NO: AW3045SVD-NP
 - Poles: 02-12P
 - Housing Material: LCP UL94 V-0 Black
 - Contact Area Plating: Tin-Plated
 - The Dimension Marked “▼” Must Be Recorded

Poles	Part No.	Dimensions (mm)		
		A	B	C
2	AW3045SVD-02	9.65	3.00	7.30
3	AW3045SVD-03	12.65	6.00	10.30
4	AW3045SVD-04	15.65	9.00	13.30
5	AW3045SVD-05	18.65	12.00	16.30
6	AW3045SVD-06	21.65	15.00	19.30
7	AW3045SVD-07	24.65	18.00	22.30
8	AW3045SVD-08	27.65	21.00	25.30
9	AW3045SVD-09	30.65	24.00	28.30
10	AW3045SVD-10	33.65	27.00	31.30
11	AW3045SVD-11	36.65	30.00	34.30
12	AW3045SVD-12	39.65	33.00	37.30

Unless otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

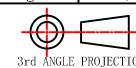
SCALE: As Shown	UNIT: mm
DRAW Jack Bao	DATE 07/09/2017
CHECK BobYang	DATE 07/09/2017

Antenk® ANTENK ELECTRONICS CO., LTD
[Http://www.antenk.com](http://www.antenk.com)
 E-mail:sales@antenk.com

TITLE:MX3.0mm SMT 180° With forking grounding Wafer Connector Series

DRAWING NO: AW3045SVD-NP

PRODUCT NO: AW3045SVD-NP



REV	DESCRIPTION	DATE
1	2	3
1	2	3